



# PJM20C60TM

## N and P-Channel Complementary Power MOSFET

### Features

#### ● N-Channel

$V_{DS}=60V, I_D=25A$

$R_{DS(on)}<40m\Omega @ V_{GS}=10V$

$R_{DS(on)}<60m\Omega @ V_{GS}=4.5V$

#### ● P-Channel

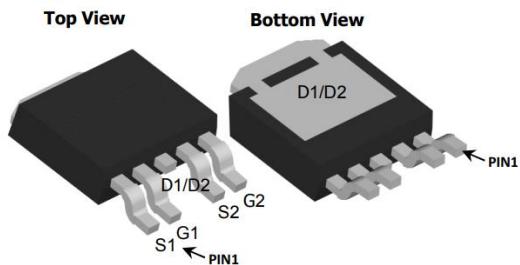
$V_{DS}=-60V, I_D=-19A$

$R_{DS(on)}<90m\Omega @ V_{GS}=-10V$

$R_{DS(on)}<100m\Omega @ V_{GS}=-4.5V$

- Advanced trench technology to provide excellent  $R_{DS(on)}$

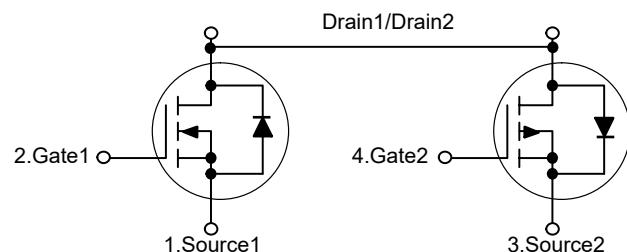
### TO-252-4L



### Applications

- Motor Drive Applications
- Networking
- Half/Full Bridge Topology

### Schematic Diagram



### Absolute Maximum Ratings

Ratings at 25°C Junction temperature unless otherwise specified.

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	60	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		V
Drain Current-Continuous at $V_{GS}=10V$ <sup>Note1</sup>	$I_D$	25	-19	A
Drain Current-Pulsed <sup>Note2</sup>	$I_{DM}$	60	-30	A
Single Pulse Avalanche Energy <sup>Note3</sup>	$E_{AS}$	22	29.8	mJ
Avalanche Current	$I_{AS}$	21	-19	A
Maximum Power Dissipation <sup>Note4</sup>	$P_D$	50	50	W
Junction Temperature	$T_J$	175		°C
Storage Temperature Range	$T_{STG}$	-55 to +175		°C

### Thermal Characteristics

Thermal Resistance, Junction-to-Ambient <sup>Note2</sup>	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-to-Case <sup>Note2</sup>	$R_{\theta JC}$	3	°C/W

**N-Channel****Electrical Characteristics**(T<sub>J</sub>=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	65	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	--	--	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
Gate Threshold Voltage <sup>Note2</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.75	2.5	V
Drain-Source On-Resistance <sup>Note2</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	--	32	40	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	--	48	60	mΩ
Forward Transconductance <sup>Note2</sup>	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =4A	--	28	--	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	--	1027	--	pF
Output Capacitance	C <sub>oss</sub>		--	65	--	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		--	45	--	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =4A V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω	--	3	--	nS
Turn-on Rise Time	t <sub>r</sub>		--	34	--	nS
Turn-off Delay Time	t <sub>d(off)</sub>		--	23	--	nS
Turn-off Fall Time	t <sub>f</sub>		--	6	--	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =48V, I <sub>D</sub> =4A, V <sub>GS</sub> =4.5V	--	19	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	2.6	--	nC
Gate-Drain Charge	Q <sub>gd</sub>		--	4.1	--	nC
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>Note2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A	--	--	1.2	V
Diode Forward Current <sup>Note1,5</sup>	I <sub>S</sub>		--	--	2.5	A

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width≤ 300us , duty cycle ≤ 2%
- 3.The E<sub>AS</sub> data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=21A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**P-Channel****Electrical Characteristics**(T<sub>J</sub>=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	-V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	60	65	--	V
Zero Gate Voltage Drain Current	-I <sub>DSS</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V	--	--	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
Gate Threshold Voltage <sup>Note2</sup>	-V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	1.2	1.75	2.5	V
Drain-Source On-Resistance <sup>Note2</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A	--	70	90	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A	--	88	100	mΩ
Forward Transconductance <sup>Note2</sup>	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A	--	8.5	--	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	--	1137	--	pF
Output Capacitance	C <sub>oss</sub>		--	76	--	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		--	50	--	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, I <sub>D</sub> =-1A V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω	--	9.2	--	nS
Turn-on Rise Time	t <sub>r</sub>		--	20.1	--	nS
Turn-off Delay Time	t <sub>d(off)</sub>		--	46.7	--	nS
Turn-off Fall Time	t <sub>f</sub>		--	9.4	--	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-48V, I <sub>D</sub> =-3A, V <sub>GS</sub> =-4.5V	--	12.1	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	2.2	--	nC
Gate-Drain Charge	Q <sub>gd</sub>		--	6.3	--	nC
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>Note2</sup>	-V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =-1A	--	--	1.2	V
Diode Forward Current <sup>Note1,5</sup>	-I <sub>s</sub>		--	--	2.5	A

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width≤ 300us , duty cycle ≤ 2%
- 3.The E<sub>AS</sub> data shows Max. rating . The test condition is V<sub>DD</sub>=-25V,V<sub>GS</sub>=-10V,L=0.1mH,I<sub>AS</sub>=-19A
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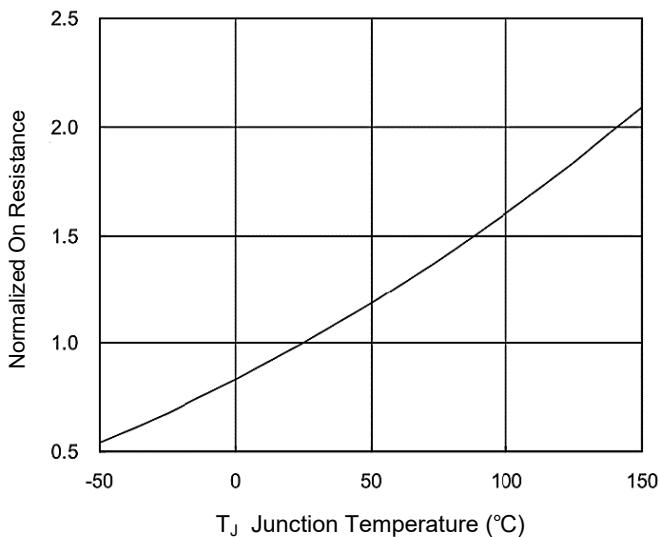
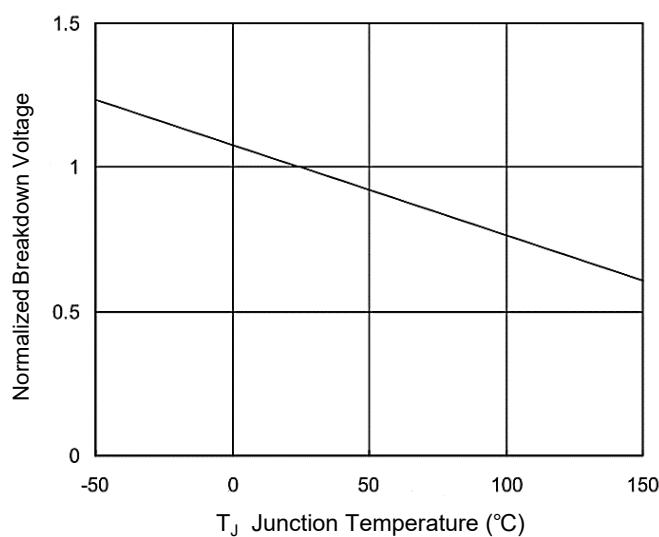
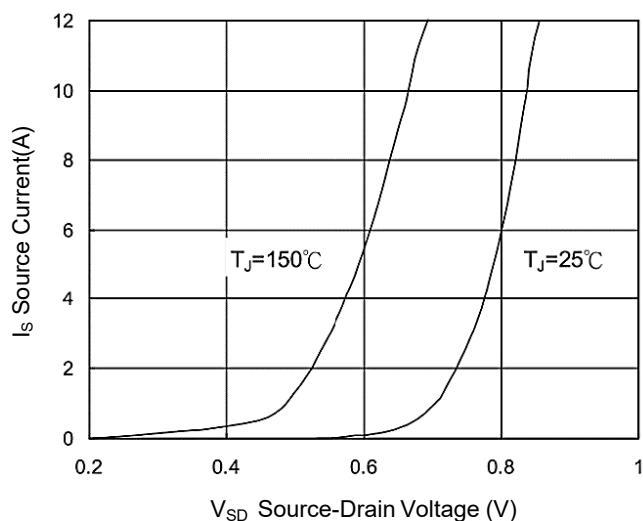
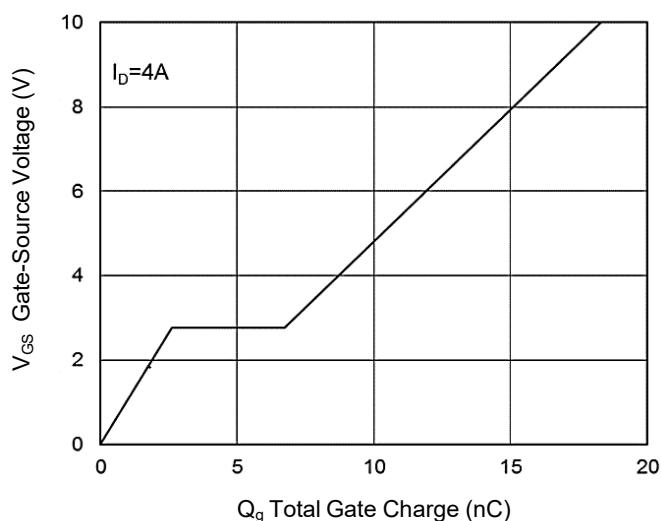
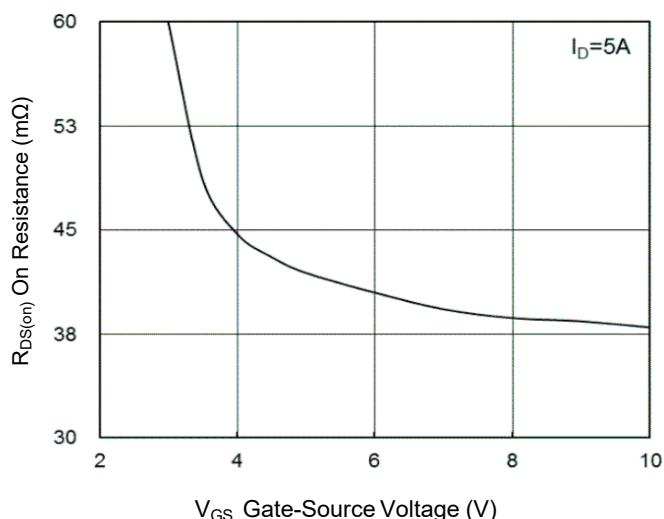
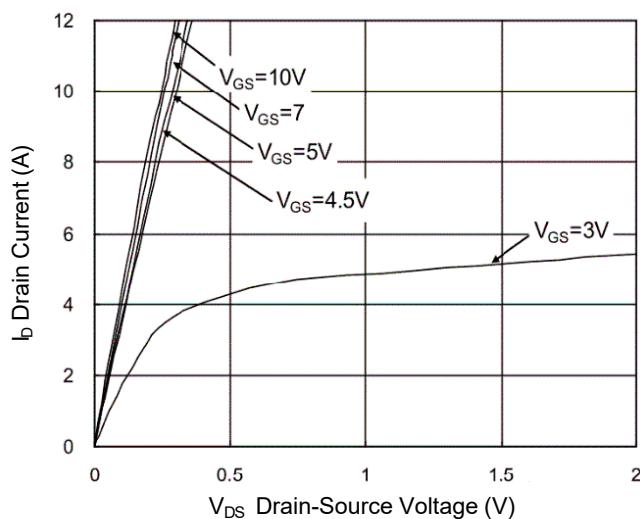


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## N-Channel

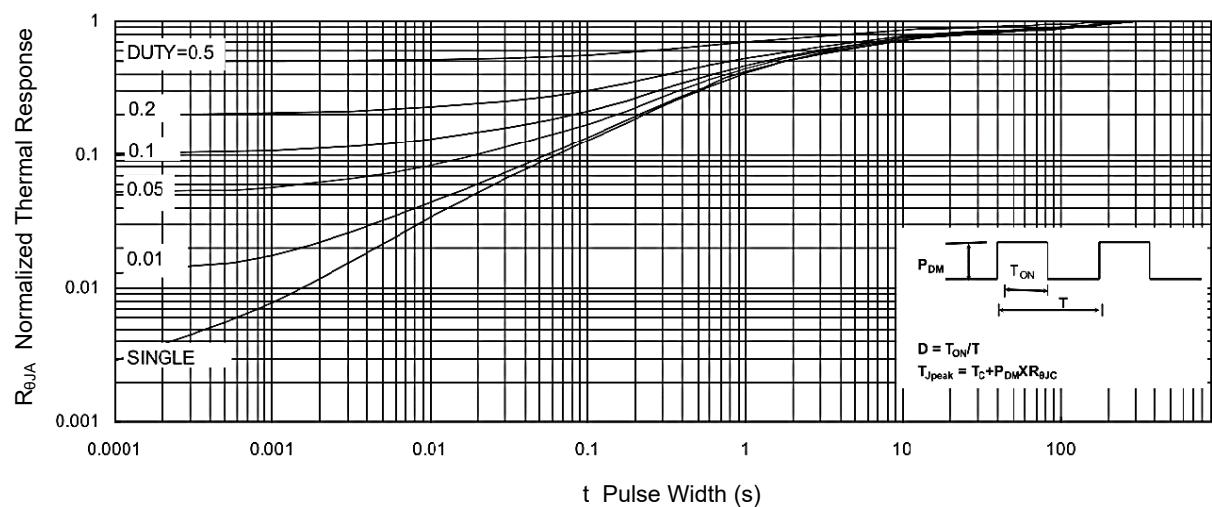
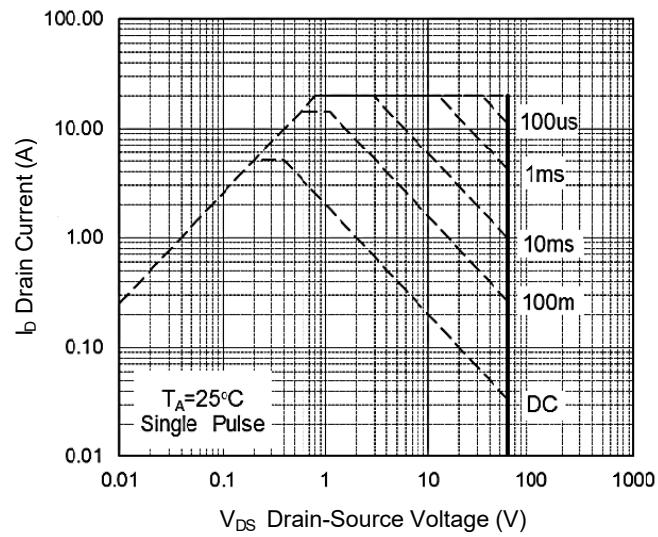
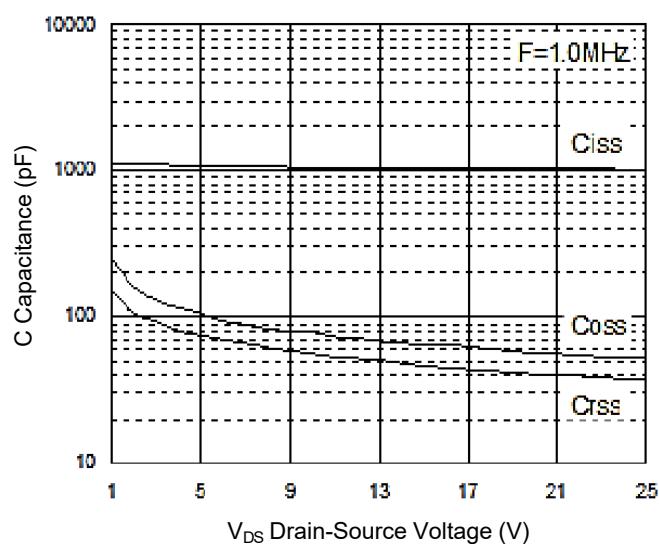
### Typical Characteristics Curves





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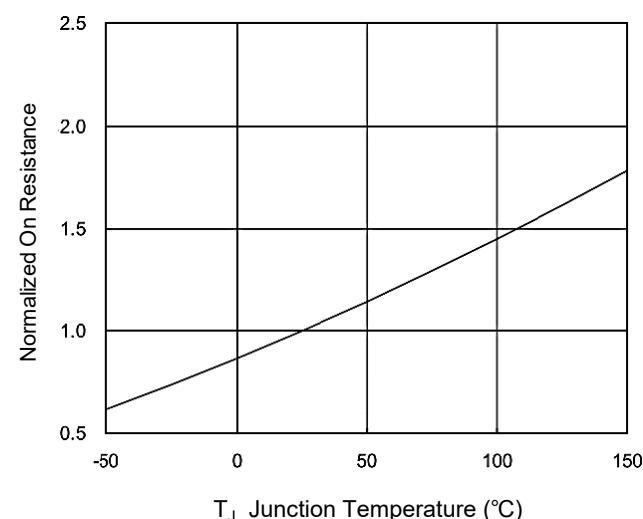
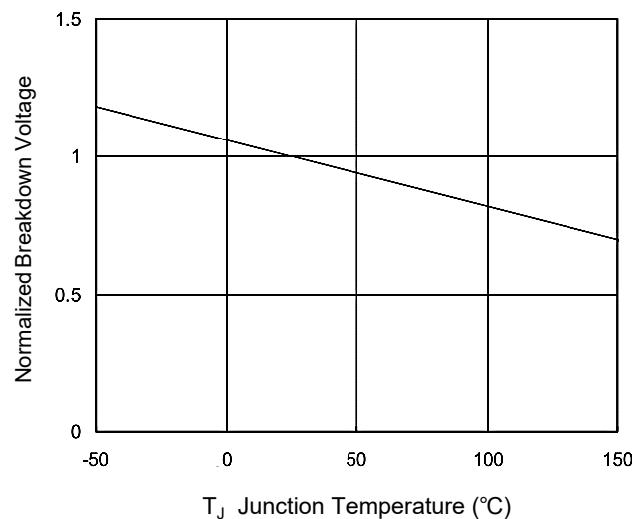
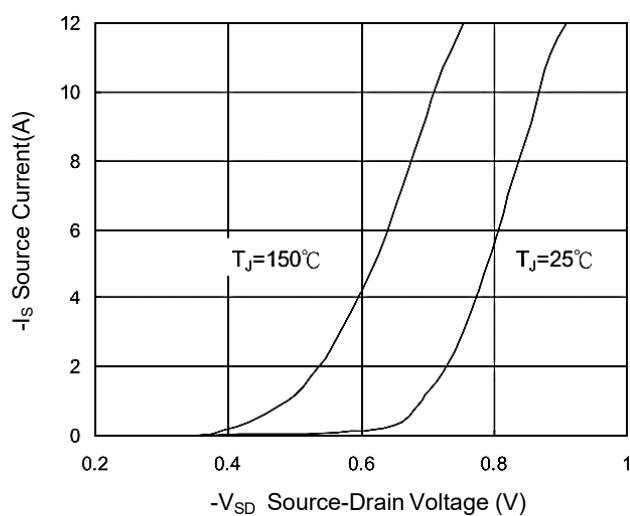
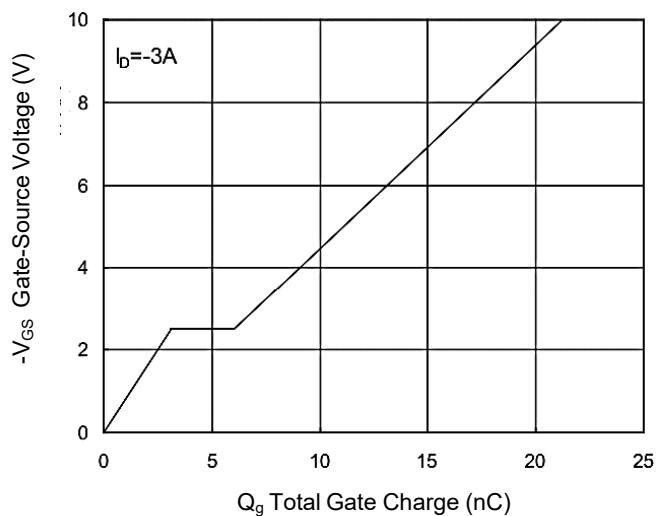
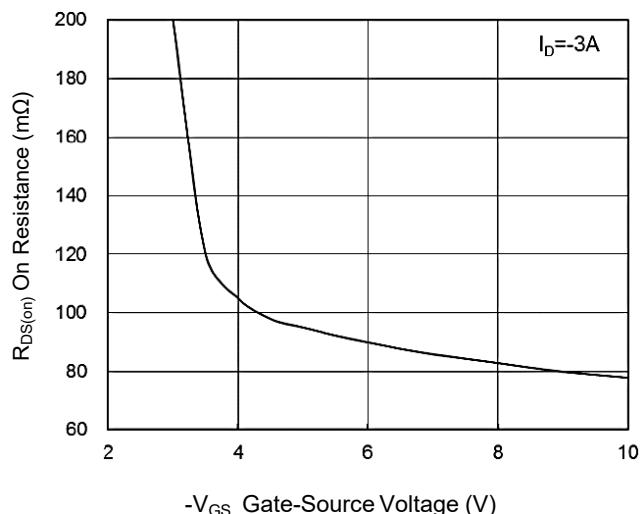
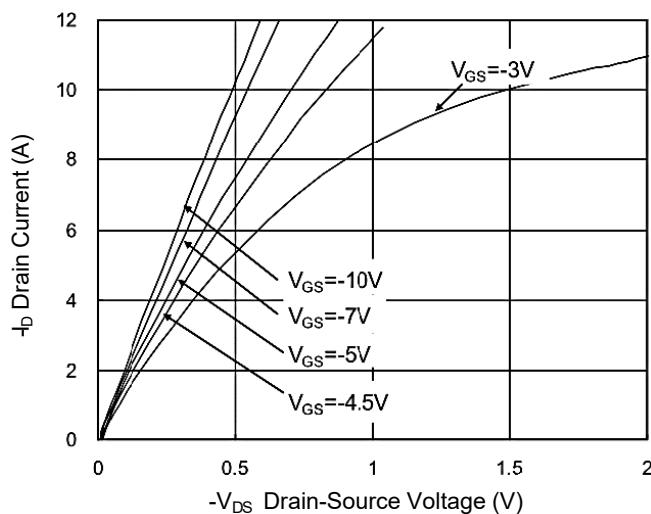


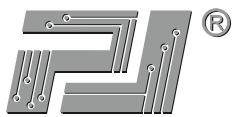
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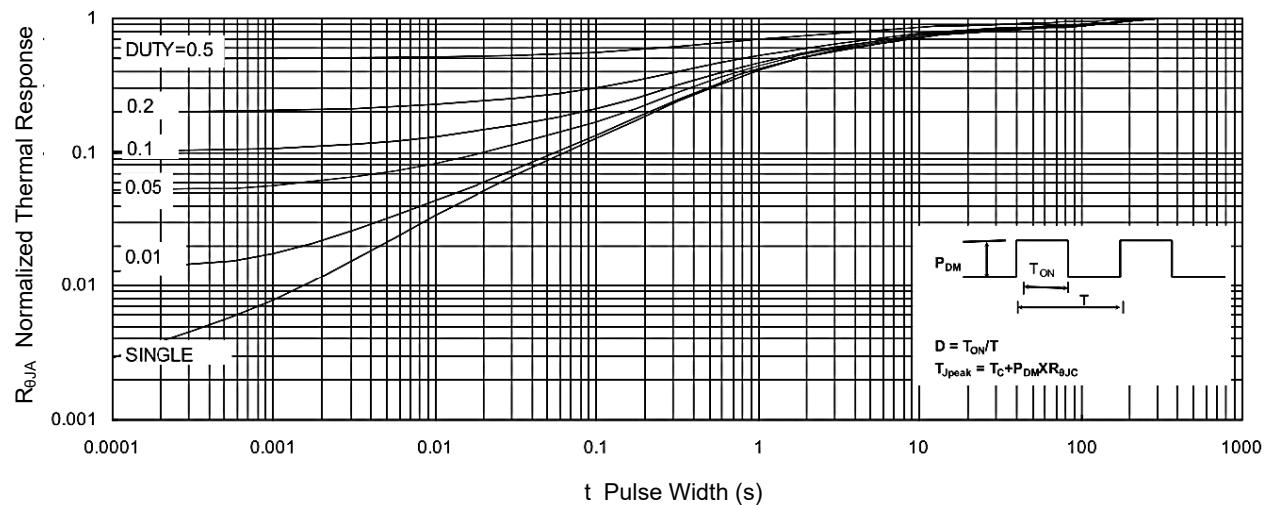
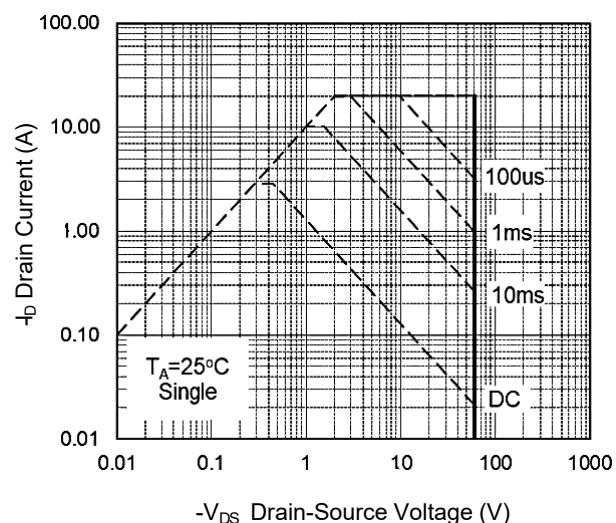
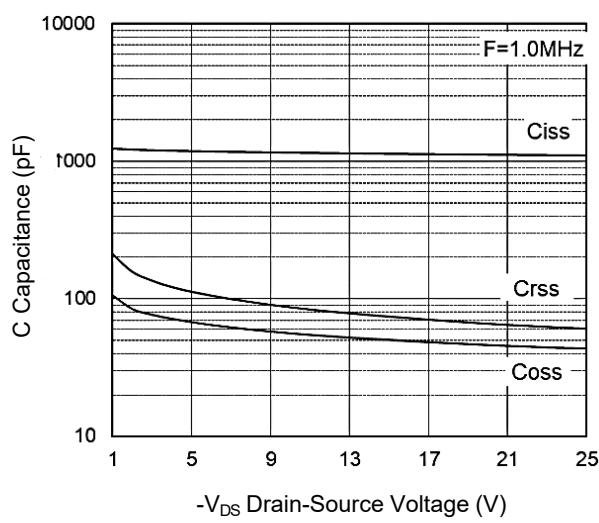
### Typical Characteristics Curves

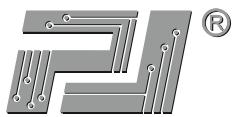




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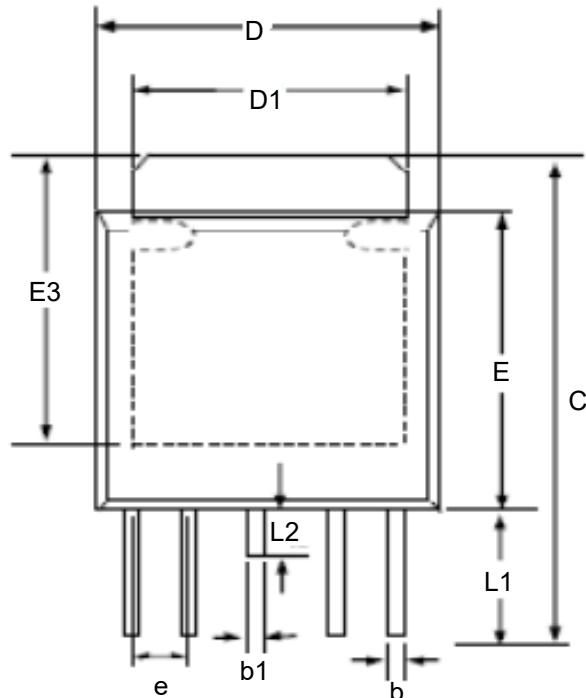




## Package Outline

TO-252-4L

Dimensions in mm



Symbol	Millimeters		
	Min.	Typ.	Max.
D	6.30	6.55	6.80
D1	4.80	5.35	5.90
C	9.30	9.75	10.20
E	5.30	5.80	6.30
E3	4.50	5.15	5.80
L	0.90	1.35	1.80
L1	2.00	2.53	3.05
L2	0.50	0.85	1.20
b	0.30	0.50	0.70
b1	0.40	0.60	0.80
A	2.10	2.30	2.50
A2	0.40	0.53	0.65
A1	0.00	0.10	0.20
e	1.20	1.30	1.40

